

HEAT DISSIPATING DEVICE

ABSTRACT OF THE DISCLOSURE

5 A heat dissipating device is provided for reducing the high production costs of conventional heat dissipating devices. The heat dissipating device is mounted on a heat generating object and includes a heat conductive base having a plurality of insertion holes. At least one heat generating region is formed in a contact area between the heat conductive base and a heat source
10 of the heat generating object. A plurality of heat dissipating columns is disposed in the at least one heat generating region and is respectively inserted into and positioned in the plurality of insertion holes. Each heat dissipating column includes a heat conductive silicone layer disposed on an outer periphery thereof.

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FIG. 2